



TEA6430

AUDIO CELLULAR MATRIX

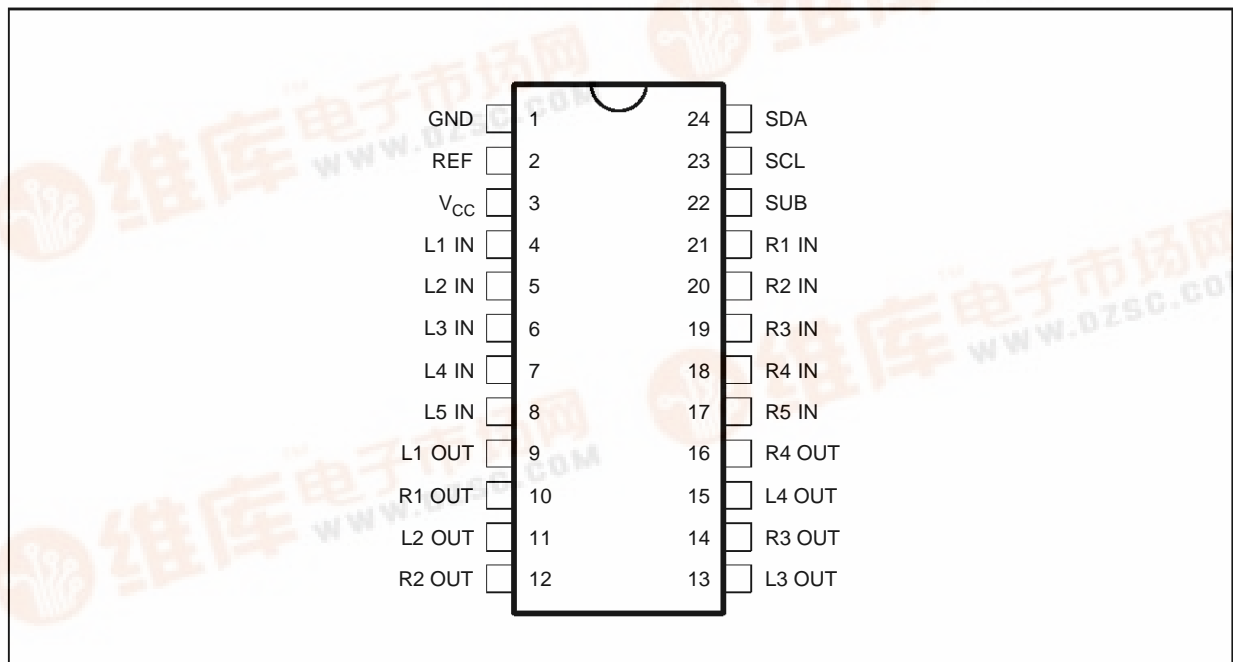
- 5 STEREO INPUTS - 4 STEREO OUTPUTS
- 3-STATE OPERATION FOR EACH OUTPUT
- GAIN OUTPUT CONTROL
0dB/2/4/6dB/MUTE FOR EACH
- VERY LOW NOISE AND DISTORTION
- I²C BUS CONTROL
- 4 SUB-ADDRESS FACILITY
- 90dB CROSSTALK BETWEEN ANY INPUT AND OUTPUT

DESCRIPTION

The TEA6430 switches 5 stereo inputs on 4 stereo outputs, providing the customer with high quality sound (low noise, low distortion). The 4 stereo outputs can be set separately in high impedance state, to enable parallel connection of several devices (up to 4). All functions are controlled through the I²C bus.



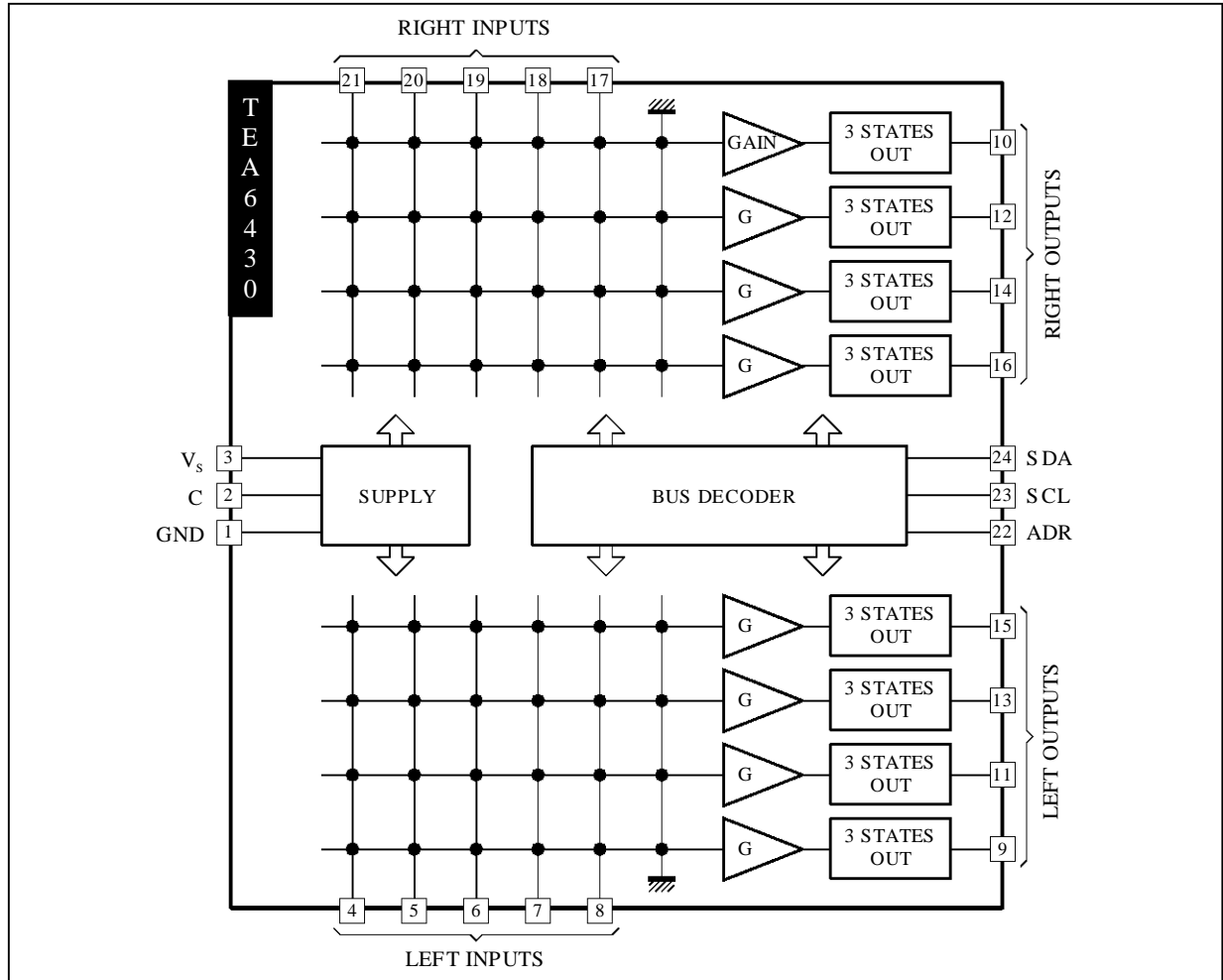
PIN CONNECTIONS



6430-01.EPS

TEA6430

BLOCK DIAGRAM



The output loads have to be larger than 2kΩ (typical 10kΩ) and 1500pF

ABSOLUTE MAXIMUM RATINGS

Symbol	Parameter	Value	Unit
V_{CC}	Supply Voltage	12	V
V_i	Voltage at Pin i to GND	0, V_{CC}	V
T_{oper}	Operating Ambient Temperature	0, + 70	°C
T_{stg}	Storage Temperature	-20, + 150	°C

THERMAL DATA

Symbol	Parameter	Value	Unit
$R_{th(j-a)}$	Junction-ambient Thermal Resistance	75	°C/W

ELECTRICAL CHARACTERISTICS

($V_{CC} = 8V$, $T_{amb} = 25^{\circ}C$, $R_L = 10k\Omega$, $R_G = 600\Omega$, $f = 1kHz$, $G = 0dB$, $V_{IN} = 0.5V_{RMS}$;
3-state is controlled by I²C bus, unless otherwise specified)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
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SUPPLY

V_{CC}	Supply Voltage		7.2	8	10.2	V
I_{CC}	Supply Current		4	7	10	mA
RR	Ripple Rejection	$V_{IN} = 0.5V_{RMS}$, $f = 1kHz$	70			dB

AUDIO INPUTS

V_{IN}	Max. Signal Amplitude		2			V_{RMS}
V_{DC}	Input DC Level			$V_{CC}/2$		V
R_I	Input Resistance		30	50	100	k Ω

AUDIO OUTPUTS

R_{OUT}	Output Resistance			60	100	Ω
Z_{HI}	Output "off" Impedance	$f = 20kHz$, output disabled	50			k Ω
V_{OFF}	DC Offset Change	Switching between inputs, see note 1		0.1	5	mV
V_{OUT}	Output DC Level		$0.4 V_{CC}$	$V_{CC}/2$	$0.6 V_{CC}$	V
V_N	Output Noise Voltage	$B = 20-20kHz$, flat, see note 2		2.5		μV
G	Gain	$B = 20-20kHz$, $R_L = 2k\Omega$	-0.5	0	+0.5	dB
	Isolation "off" State	$f = 1kHz$, output disabled	85			dB
THD	Distortion	$V_{IN} = 1V_{RMS}$, $f = 1kHz$		0.01	0.05	%
V_{CL}	Clipping Level	$d = 0.3\%$	2	2.3		V_{RMS}
C_S	L, R Channel Separation	$f = 1kHz$	-85			dB
	Crosstalk Audio Channels	$f = 1kHz$, see note 3	-85	-100		dB
C_L	Load Capacitance		1500			pF

- Notes :
- DC offset change is less than maximum limit, in all configurations (one or several devices in parallel), provided that the reference Pins (P2) are all connected together.
 - Flat filter according to CCIR-468-4, $B = 20Hz-20kHz$
 - Measured from any selected output which contains no signal to a set of other outputs.

6430-03.TBL

I²C BUS CHARACTERISTICS

Symbol	Parameter	Test Conditions	Standard Mode		Fast Mode		Unit
			Min.	Max.	Min.	Max.	

SCL

V _{IL}	Low Level Input Voltage		- 0.3	+ 1.5	- 0.3	+ 1.5	V
V _{IH}	High Level Input Voltage		3.0	V _{CC} + 0.5	3.0	V _{CC} + 0.5	V
I _{LI}	Input Leakage Current	V _I = 0 to V _{DD}	- 10	+ 10	- 10	+ 10	μA
f _{SCL}	Clock Frequency		0	100	0	400	kHz
t _R	Input Rise Time	1.5V to 3V		1000		300	ns
t _F	Input Fall Time	1.5V to 3V		300		300	ns
C _I	Input Capacitance			10		10	pF

SDA

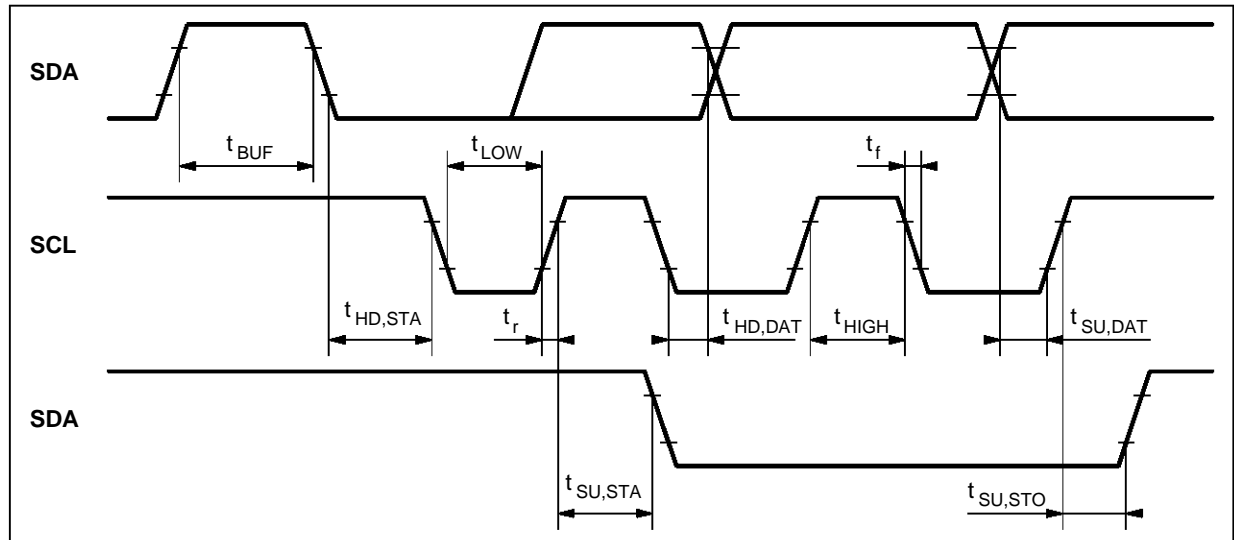
V _{IL}	Low Level Input Voltage		- 0.3	+ 1.5	- 0.3	+ 1.5	V
V _{IH}	High Level Input Voltage		3.0	V _{CC} + 0.5	3.0	V _{CC} + 0.5	V
I _{LI}	Input Leakage Current	V _I = 0 to V _{DD}	- 10	+ 10	- 10	+ 10	μA
C _I	Input Capacitance			10		10	pF
t _R	Input Rise Time	1.5V to 3V		1000		300	ns
t _F	Input Fall Time	1.5V to 3V		300		300	ns
V _{OL}	Low Level Output Voltage	I _{OL} = 3mA		0.4		0.4	V
t _F	Output Fall Time	3V to 1.5V		250		250	ns
C _L	Load Capacitance			400		400	pF

TIMING

t _{LOW}	Clock Low Period		4.7		1.3		ms
t _{HIGH}	Clock High Period		4.0		0.6		ms
t _{SU, DAT}	Data Set-up Time		250		100		ns
t _{HD, DAT}	Data Hold Time		0	340	0	340	ns
t _{SU, STO}	Set-up Time from Clock High to Stop		4.0		0.6		μs
t _{BUF}	Start Set-up Time following a Stop		4.7		1.3		μs
t _{HD, STA}	Start Hold Time		4.0		0.6		μs
t _{SU, STA}	Start Set-up Time following Clock Low-to-High Transition		4.7		0.6		μs

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Figure 1 : I²C Bus Timing



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I²C BUS SELECTION**I²C Bus Slave Address**

Address	A6	A5	A4	A3	A2	A1	A0	R/W
Value	1	0	0	1	1	A1	A0	0

Sub-address I²C

Symbol	Parameter	Conditions	Pin 22 Voltage (typ.)	Unit
Vsub	Slave address HEXA	Sub-address (see note)		
1	98	A1 = 0, A0 = 0	GND	V
2	9E	A1 = 1, A0 = 1	V _{CC}	V
3	9C	A1 = 1, A0 = 0	1/3	V _{CC}
4	9A	A1 = 0, A0 = 1	2/3	V _{CC}

Note : The first3 levels are defined by connecting the sub-address pin to the appropriate level. Sub-address 4 will be selected when this pin is left open.

Data Byte

	b7	b6	b5	b4	b3	b2	b1	b0	Action
	T	01	00	G1	G0	I2	I1	I0	
Input Select	*	*	*	*	*	0	0	0	IN1
	*	*	*	*	*	0	0	1	IN2
	*	*	*	*	*	0	1	0	IN3
	*	*	*	*	*	0	1	1	IN4
	*	*	*	*	*	1	0	0	IN5
	*	*	*	*	*	1	0	1	Mute
Output Select	*	0	0	*	*	*	*	*	OUT1
	*	0	1	*	*	*	*	*	OUT2
	*	1	0	*	*	*	*	*	OUT3
	*	1	1	*	*	*	*	*	OUT4
Gain	*	*	*	0	0	*	*	*	6dB
	*	*	*	0	1	*	*	*	4dB
	*	*	*	1	0	*	*	*	2dB
	*	*	*	1	1	*	*	*	0dB
Tri-state	0	*	*	*	*	*	*	*	Low impedance Tri-state
	1	*	*	*	*	*	*	*	

Example : 00111100 enables L(R)2 out and connect it with a gain of 0dB to L(R)5 in.

Power On Reset

When active : outputs in 3-state. All outputs are disabled and L(R)5 is selected to drive all outputs. Gain = 0dB.

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
Reset	Start of Reset	Incr. V _{CC}			2.5	V
	End of Reset	Decr. V _{CC}			4.2	V
		Incr. V _{CC}	4.5			V

TYPICAL PERFORMANCES

Figure 1 : Supply Current as a Function of Supply Voltage

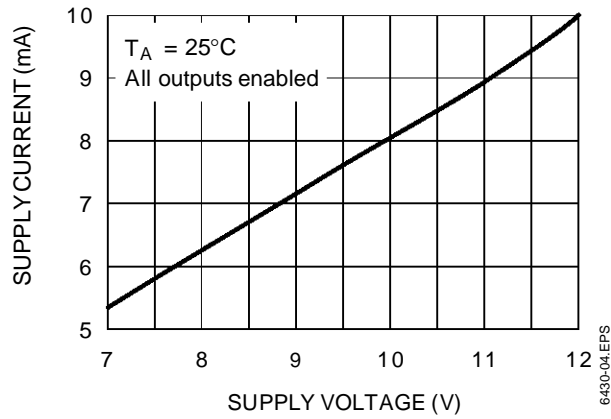


Figure 2 : Supply Current as a Function of Temperature

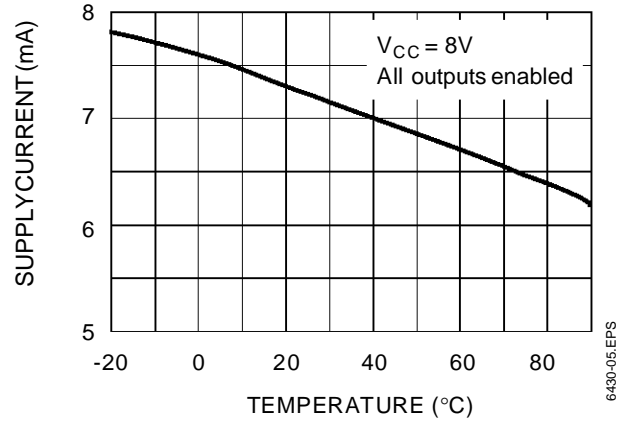


Figure 3 : Ripple Rejection as a Function of Supply Voltage

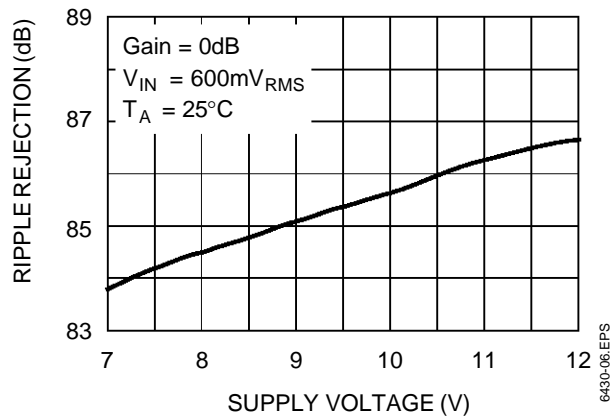


Figure 4 : Ripple Rejection as a Function of Temperature

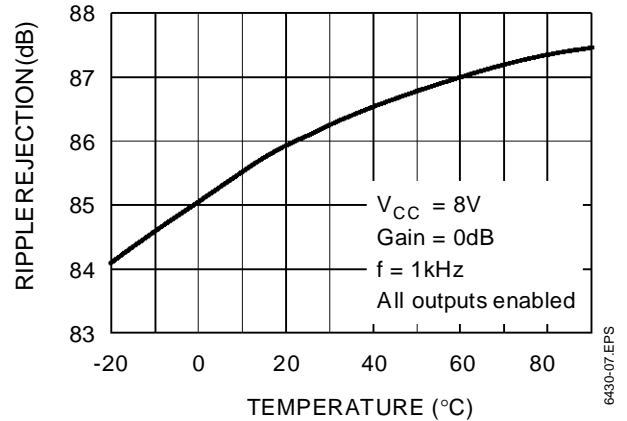


Figure 5 : Ripple Rejection as a Function of Gain

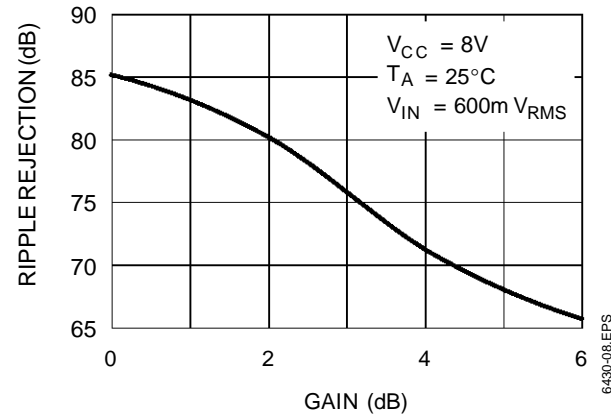
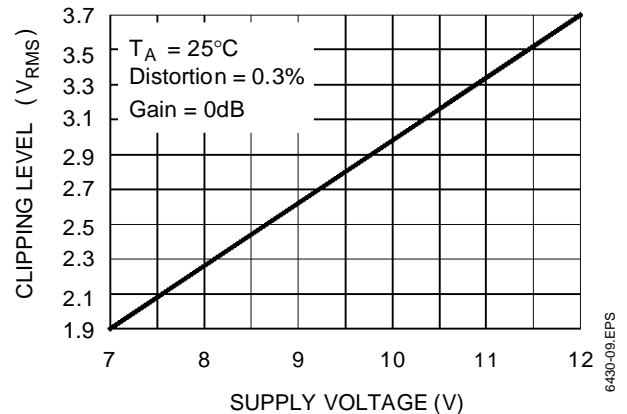


Figure 6 : Clipping Level as a Function of Supply Voltage



TYPICAL PERFORMANCES (continued)

Figure 7 : Distortion as a Function of Input Level

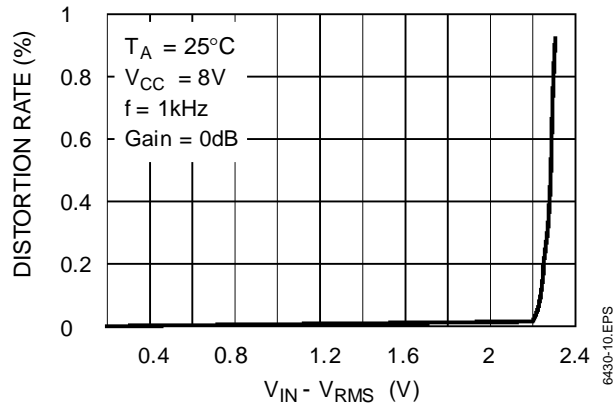


Figure 8 : Distortion as a Function of Gain

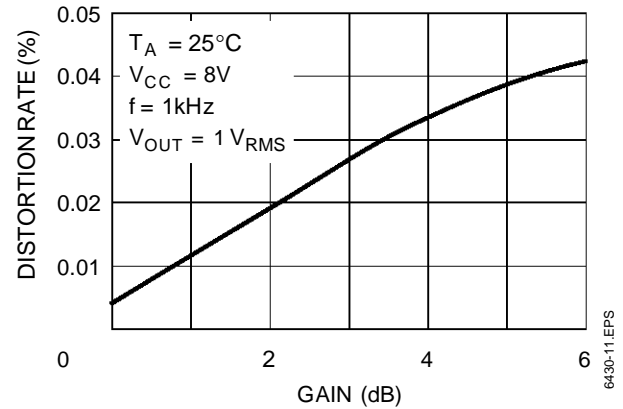


Figure 9 : Crosstalk Level as a Function of Frequency (Gain = 0dB)

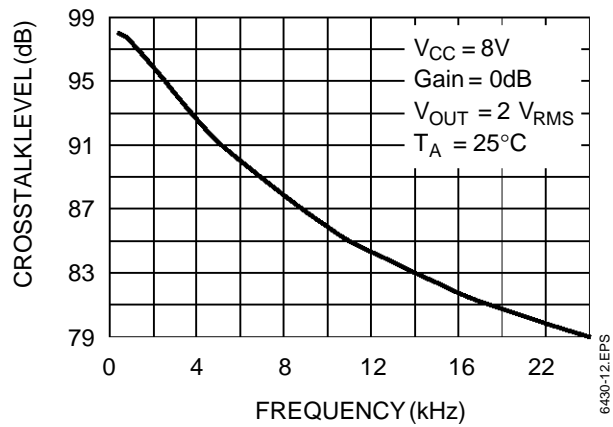
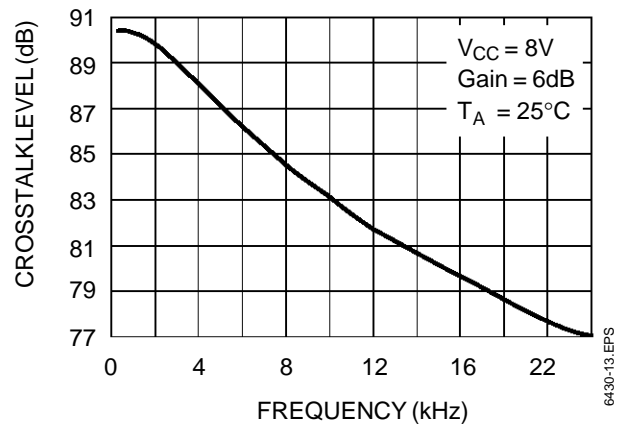


Figure 10 : Crosstalk Level as a Function of Frequency (Gain = 6dB)



PIN CONFIGURATIONS

Figure 11 : Audio IN

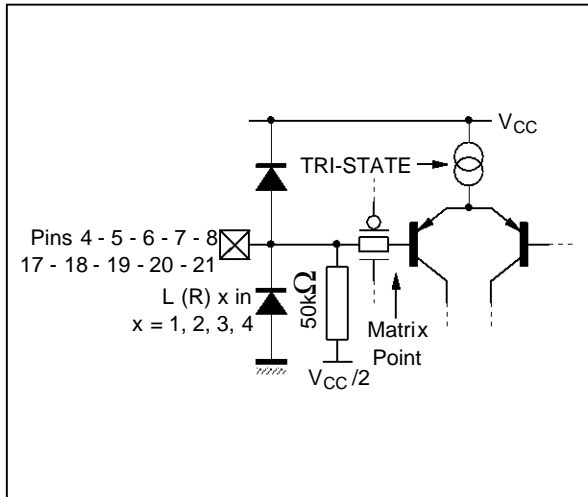


Figure 12 : Audio OUT

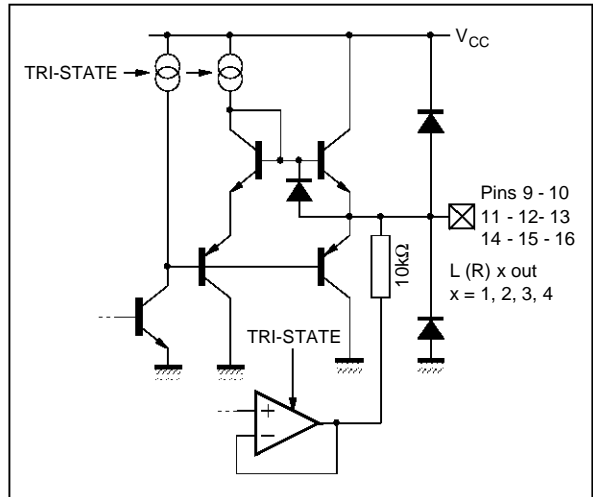


Figure 13 : PROG

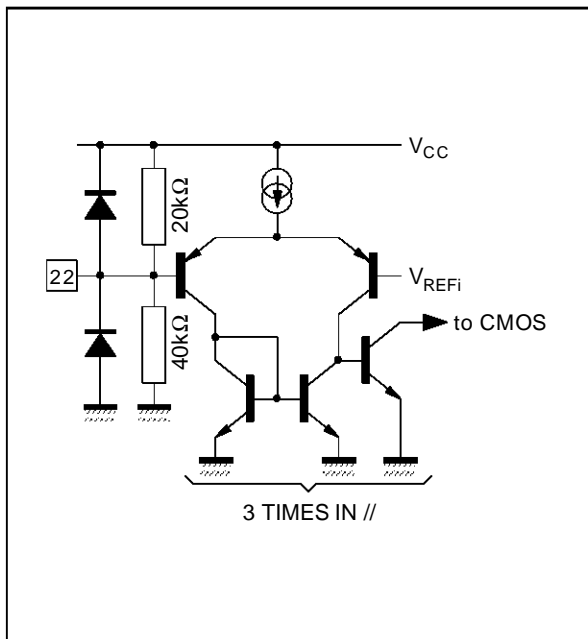
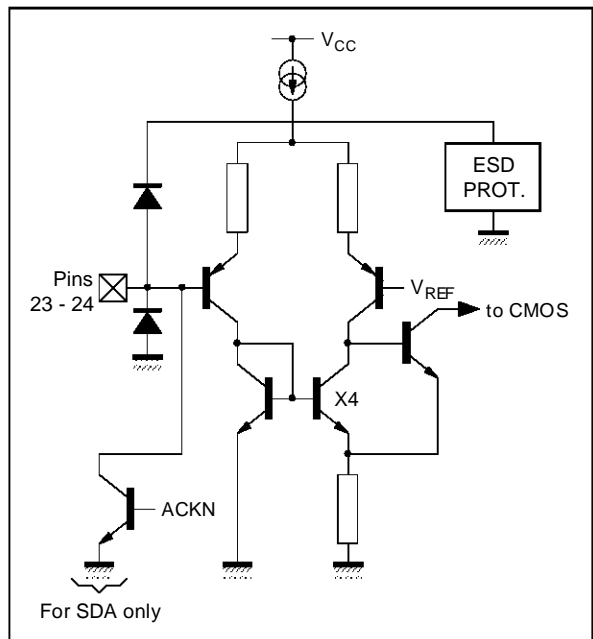
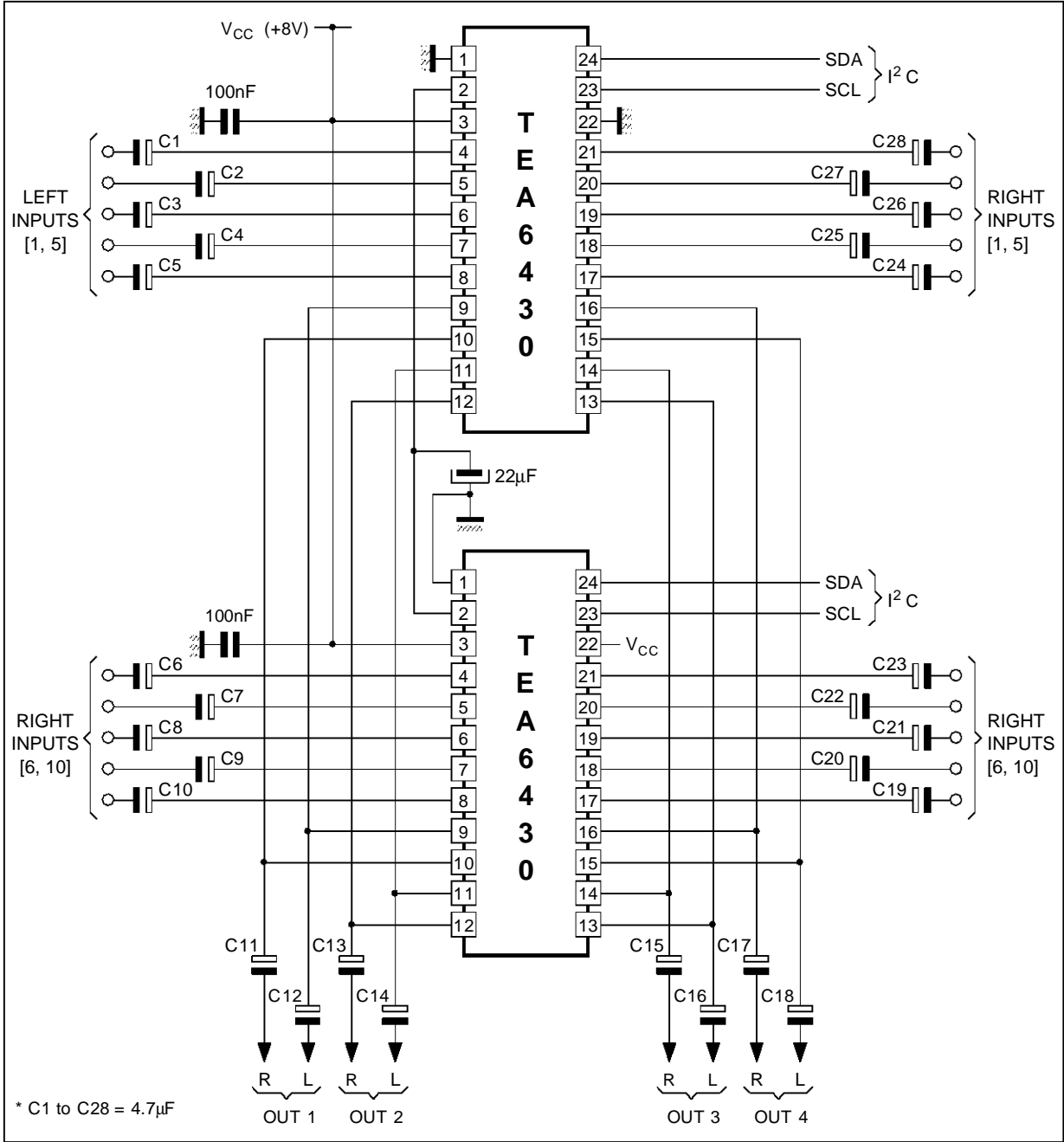


Figure 14 : Bus Inputs



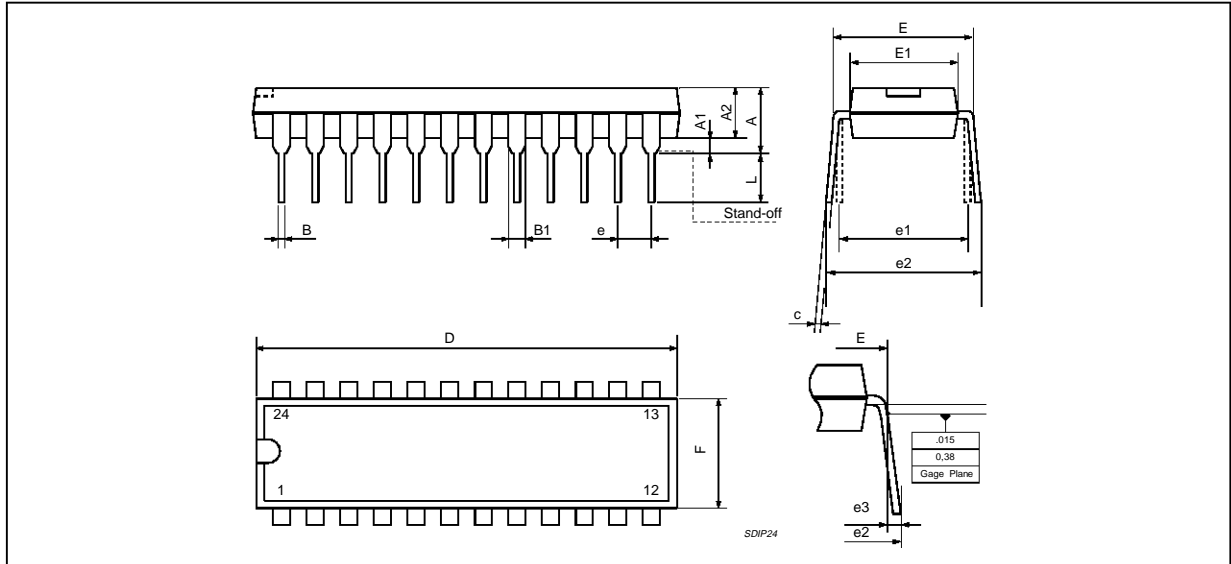
TYPICAL APPLICATION



6430-18.EPS

TEA6430

PACKAGE MECHANICAL DATA 24 PINS - PLASTIC SHRINK DIP



PMSDIP24.EPS

Dimensions	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A			5.08			0.20
A1	0.51			0.020		
A2	3.05	3.30	4.57	0.120	0.130	0.180
B	0.36	0.46	0.56	0.0142	0.0181	0.0220
B1	0.76	1.02	1.14	0.030	0.040	0.045
C	0.23	0.25	0.38	0.0090	0.0098	0.0150
D	22.61	22.86	23.11	0.890	0.90	0.910
E	7.62		8.64	0.30		0.340
E1	6.10	6.40	6.86	0.240	0.252	0.270
e		1.778			0.070	
e1		7.62			0.30	
e2			10.92			0.430
e3			1.52			0.060
L	2.54	3.30	3.81	0.10	0.130	0.150

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